Manufacturing Tool for Wafer Level Package and Method of Placing dice

ABSTRACT OF THE INVENTION

A tool of wafer level package comprises a first base, an elastic material and a second base. The elastic material is coated on the first base, and the elastic material has viscosity in common state to adhere a plurality of dice. The second base is coated by adhesive material to adhere the dice. The plurality of dice are departed from the elastic material by a special environment after adhering.

(Fig. 7)